## 650W, 50V High Power RF LDMOS FETs

## Description

The YC0565VPX is a 650-watt capable, high performance, unmatched LDMOS FET, designed for wide-band commercial and industrial applications with frequencies HF to 0.5 GHz . It can be used for both CW and pulse applications. It is featured for high power and high ruggedness, suitable for Industrial, Scientific and Medical application, as well as FM radio, VHF TV and Aerospace applications.

- Typical performance(on 325 MHz test board with device soldered):
$V_{D D}=50$ Volts, $I_{D Q}=200 \mathrm{~mA}$, Pulsed CW.(100us, 10\%), Vgs=3.24V, YC0565VPX $50 \mathrm{~V}, \mathrm{dq}=230 \mathrm{~mA}$

| Freq (MHz) | P3dB (W) | Gain (dB) | Eff (\%) |
| :---: | :---: | :---: | :---: |
| 325 | 670 | 15.5 | 68 |

- Recommended driver: MR2002VP or MU1503V
- Application board for 2-30/27/40/225/325MHz upon request


## Features

- High Efficiency and Linear Gain Operations
- Integrated ESD Protection
- Excellent thermal stability, low HCl drift
- Large Positive and Negative Gate/Source Voltage Range for Improved Class C Operation
- Pb-free, RoHS-compliant


## Suitable Applications

- $30-88 \mathrm{MHz}$ (Ground communication)
- $54-88 \mathrm{MHz}$ (TV VHF I)
- $88-108 \mathrm{MHz}$ (FM)
- $160-230 \mathrm{MHz}$ (TV VHF III)
- $136-174 \mathrm{MHz}$ (Commercial ground communication)
- Laser Exciter
- Synchrotron
- MRI
- Plasma generator
- Weather Radar

Table 1. Maximum Ratings

| Rating | Symbol | Value | Unit |
| :--- | :---: | :---: | :---: |
| Drain--Source Voltage | $\mathrm{V}_{\text {DSs }}$ | +135 | Vdc |
| Gate--Source Voltage | $\mathrm{V}_{\mathrm{GS}}$ | -10 to +10 | Vdc |
| Operating Voltage | $\mathrm{V}_{\mathrm{DD}}$ | +55 | Vdc |
| Storage Temperature Range | Tstg | -65 to +150 | ${ }^{\circ} \mathrm{C}$ |
| Case Operating Temperature | $\mathrm{T}_{\mathrm{C}}$ | +150 | ${ }^{\circ} \mathrm{C}$ |
| Operating Junction Temperature | $\mathrm{T}_{J}$ | +225 | ${ }^{\circ} \mathrm{C}$ |

Table 2. Thermal Characteristics

| Characteristic | Symbol | Value | Unit |
| :--- | :---: | :---: | :---: |
| Thermal Resistance, Junction to Case | RөJC |  |  |
| $T_{C}=85^{\circ} \mathrm{C}, \mathrm{T}_{J}=200^{\circ} \mathrm{C}, \mathrm{DC}$ test |  | 0.22 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |

Table 3. ESD Protection Characteristics
Test Methodology $\quad$ Class $\quad$.

| Human Body Model (per JESD22--A114) |  |
| :--- | :--- |

Table 4. Electrical Characteristics ( $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ unless otherwise noted)

| Characteristic | Symbol | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: |

DC Characteristics (per half section)

| Drain-Source Voltage $\mathrm{V}_{\mathrm{GS}}=0, \mathrm{I}_{\mathrm{DS}}=1.0 \mathrm{Ma}$ | $V_{\text {(BR)JSs }}$ |  | 135 |  | V |
| :---: | :---: | :---: | :---: | :---: | :---: |
| Zero Gate Voltage Drain Leakage Current $\left(V_{D S}=75 \mathrm{~V}, \mathrm{~V}_{\mathrm{GS}}=0 \mathrm{~V}\right)$ | $\mathrm{I}_{\text {DS }}$ | -— | —— | 1 | $\mu \mathrm{A}$ |
| Zero Gate Voltage Drain Leakage Current $\left(\mathrm{V}_{\mathrm{DS}}=50 \mathrm{~V}, \mathrm{~V}_{\mathrm{GS}}=0 \mathrm{~V}\right)$ | $\mathrm{l}_{\text {ss }}$ | -— | —— | 1 | $\mu \mathrm{A}$ |
| Gate--Source Leakage Current $\left(\mathrm{V}_{\mathrm{GS}}=10 \mathrm{~V}, \mathrm{~V}_{\mathrm{DS}}=0 \mathrm{~V}\right)$ | $\mathrm{I}_{\text {gss }}$ | —— | —— | 1 | $\mu \mathrm{A}$ |
| Gate Threshold Voltage $\left(V_{D S}=50 \mathrm{~V}, I_{D}=600 \mu \mathrm{~A}\right)$ | $\mathrm{V}_{\text {Gs }}(\mathrm{th})$ | —— | 2.65 | —— | V |
| Gate Quiescent Voltage <br> ( $\mathrm{V}_{\mathrm{DD}}=50 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=230 \mathrm{~mA}$, Measured in Functional Test) | $V_{\text {GS(Q) }}$ | —— | 3.24 | -- | V |
| Drain source on state resistance $(\mathrm{Vds}=0.1 \mathrm{~V}, \mathrm{Vgs}=10 \mathrm{~V})$ | Rds(on) |  | 160 |  | $\mathrm{m} \Omega$ |
| Common Source Input Capacitance $\left(\mathrm{V}_{\mathrm{GS}}=0 \mathrm{~V}, \mathrm{~V}_{\mathrm{DS}}=50 \mathrm{~V}, \mathrm{f}=1 \mathrm{MHz}\right)$ | $\mathrm{C}_{\text {ISS }}$ |  | 295 |  | pF |
| Common Source Output Capacitance $\left(\mathrm{V}_{\mathrm{GS}}=0 \mathrm{~V}, \mathrm{~V}_{\mathrm{DS}}=50 \mathrm{~V}, \mathrm{f}=1 \mathrm{MHz}\right)$ | Coss |  | 75 |  | pF |
| Common Source Feedback Capacitance $\left(\mathrm{V}_{\mathrm{GS}}=0 \mathrm{~V}, \mathrm{~V}_{\mathrm{DS}}=50 \mathrm{~V}, \mathrm{f}=1 \mathrm{MHz}\right)$ | $\mathrm{C}_{\text {RSS }}$ |  | 1.3 |  | pF |

Load Mismatch (In Yingtron Test Fixture, 50 ohm system): $V_{D D}=50 \mathrm{Vdc}, \mathrm{I}_{\mathrm{DQ}}=230 \mathrm{~mA}, \mathrm{f}=350 \mathrm{MHz}$, pulse width:100us, duty cycle:10\%

| Load 10:1 All phase angles, at 650W Pulsed CW Output Power | No Device Degradation |
| :--- | :--- |

## Reference Circuit of Test Fixture Assembly Diagram



Figure 1. Test Circuit Component Layout (325M)

Table 1. Test Circuit Component Designations and Values (325MHz)

| Component | Description | Suggested <br> Manufacturer |
| :--- | :--- | :--- |
| C1, | 20 pF | ATC800B |
| C2, C3, C4, C5, C15, C16, C17, C18, <br> C22, C23, C27, C28 | 470 pF | ATC800B |
| C6, C11, C12, C13 | 10 pF | ATC800B |
| C7, C8, C9, C10, C14, | 18 pF | ATC800B |
| C19, C20 | 4.7 pF | ATC800B |
| C21, C24, C25, C26, C29, C30 | Ceramic multilayer capacitor, 10uF, 100V |  |
| R1, R2 | $270 \Omega, 1 / 4 \mathrm{~W}$ |  |
| R3, R4 | $13 \Omega$ | 1206 |
| L1, L2 | 30 nH Air core inductance |  |
| C31, C32 | Electrolytic Capacitor ,470uF,63V |  |
| PCB | $0.508 \mathrm{~mm}[0.020$,'] thick, $\varepsilon$ r=3.48, Rogers RO4350B, 1 oz. copper |  |

## TYPICAL CHARACTERISTICS



Figure 2: Power Gain and Drain Efficiency as Function of Pout (325MHz)

## YC0565VPX LDMOS TRANSISTOR

## Package Outline

Flanged ceramic package; 2 mounting holes; 4 leads


Unit: mm
Tolerances(unless specified): x.x $\pm 0.15$ $x . x x \quad \pm 0.127$

| outline VERSION | REFERENCE |  |  | EUROPEAN <br> PROJECTION | ISSUE DATE |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  | IEC | JEDEC | JEITA |  |  |
| PKG-LBB |  |  |  |  | 11/15/2019 |

## Revision history

Table 6. Document revision history

| Date | Revision | Datasheet Status |
| :---: | :---: | :--- |
| $2019 / 12 / 17$ | Rev 1.0 | Preliminary Datasheet Creation |

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